

What is claimed is:

1. An electrical arrangement, comprising:
  - a mount device having at least one conductor
  - 5 track;
  - an electrical component mounted on the mount device and electrically connected to the at least one conductor track; and
  - a housing base plate on which the mount device is
  - 10 mounted;
  - at least one contact-making pin electrically connected to the at least one conductor track, wherein the at least one contact-making pin extends through the housing base plate,
  - 15 wherein the at least one contact-making pin touches the mount device, thereby defining a touching point, and in the area of the touching point, a connection without any bonding wire is provided between the at least one contact-making pin and the at least
  - 20 one conductor track on the mount device.
2. The electrical arrangement of Claim 1, wherein in the area of the touching point, the mount device comprises at least one recess at an edge thereof, and
- 25 wherein a contour of the at least one recess corresponds to a contour of the at least one contact-making pin.
3. The electrical arrangement of Claim 2, wherein
- 30 the recess of the mount device is semicircular.
4. The electrical arrangement of Claim 2, wherein the mount device is metallized or has a conductive layer in the area of the edge recess.
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5. The electrical arrangement of Claim 1, wherein the mount device comprises a structure defining a

contact-making hole through which the at least one contact-making pin extends.

6. The electrical arrangement of Claim 5, wherein  
5 the mount device is metallized or has a conductive layer in an area of the mount device associated with the contact-making hole.

7. The electrical arrangement of Claim 1, wherein  
10 a conductive adhesive is disposed between the mount device and the at least one contact-making pin.

8. The electrical arrangement of Claim 1, wherein  
15 the at least one contact-making pin and the at least one conductor track are soldered to one another in the area of the touching point.

9. The electrical arrangement of Claim 8, wherein  
20 the soldering is provided by means of a solder ball or a solder platelet that is applied to the at least one contact-making pin in the area of the touching point.

10. The electrical arrangement of Claim 1,  
25 wherein the electrical component comprises an electrooptical component including one of an optical transmitting element or an optical receiving element, respectively.

11. The electrical arrangement of Claim 10,  
30 wherein the optical transmitting element comprises a laser and the optical receiving element comprises a photodetector.

12. The electrical arrangement of Claim 1,  
35 wherein at least one of the bushings for the at least one contact-making pin comprises a glazed coaxial bushing.

13. The electrical arrangement of Claim 1, wherein the housing base plate is part of a TO46 housing.

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14. The electrical arrangement of Claim 1, wherein the mount device comprises a circuit mount.

15. The electrical arrangement of Claim 14, wherein the circuit mount is composed of silicon, ceramic, an organic material, or a metal provided with an isolation layer.

16. The electrical arrangement of Claim 1, wherein the electrical component comprises at least two connections that are electrically connected to a respective conductor track, and wherein the mount device touches at least two contact-making pins that extend through the housing base plate such that the contact-making pins are connected to a respective conductor track.

17. A method for producing an electrical arrangement, comprising:

25 applying at least one conductor track to a mount device;

mounting an electrical component on the mount device, wherein the electrical component is in electrical communication with the at least one conductor track;

30 mounting the mount device on a housing base plate of a housing having at least one contact-making pin extending therethrough; and

coupling the electrical component to the at least one contact-making pin,

wherein the mount device is mounted on the housing base plate such that the mount device touches the at

least one contact-making pin, thereby defining a touching point, and

wherein in the area of the touching point, a connection without any bonding wire is produced between  
5 the at least one contact-making pin and the at least one conductor track of the mount device.

18. The method of Claim 16, wherein the mount device comprises an edge recess in the area of the  
10 touching point, and wherein a contour of the edge recess corresponds to a contour of the at least one contact-making pin.

19. The method of Claim 18, wherein the edge  
15 recess is semicircular.

20. The method of Claim 18, further comprising metallizing or providing a conductive layer in the area of the edge recess of the mount device.  
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21. The method of Claim 17, wherein the mount device comprises a contact-making hole extending therethrough, through which the at least one contact-making pin extends.  
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22. The method of Claim 21, further comprising metallizing or providing a conductive layer in the area of the contact-making hole of the mount device.

23. The method of Claim 17, further comprising disposing a conductive adhesive between the mount device and the at least one contact-making pin.  
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24. The method of Claim 17, further comprising soldering together the at least one contact-making pin and the at least one conductor track in the area of the touching point.  
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25. The method of Claim 24, wherein soldering comprises applying a solder ball or a solder platelet to the at least one contact-making pin in the area of  
5 the touching point.

26. The method of Claims 17, wherein the electrical component comprises an electrooptical component.  
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27. The method of Claim 26, wherein the electrooptical component comprises an optical transmitting element or an optical receiving element, respectively.  
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28. The method of Claim 27, wherein the optical transmitting element comprises a laser or the optical receiving element comprises a photodetector, respectively, on which the mount device is mounted.  
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29. The method of Claim 17, further comprising providing a glazed coaxial bushing about the at least one contact-making pin.

30. The method of Claim 17, wherein the housing comprises a TO46 housing.  
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31. The method of Claim 17, wherein the mount device comprises a circuit mount.  
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32. The method of Claim 31, wherein the circuit mount is composed of silicon, ceramic, an organic material or a metal that is provided with an isolation layer.  
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33. The method of Claim 17, wherein the electrical component has at least two connections that

are electrically connected to a respective conductor track, and wherein the mount device is mounted on the housing base plate such that the mount device touches at least two contact-making pins that extend through  
5 the housing base plate and connect to a respective conductor track.